

## Description

The μPD424400 is a fast-page dynamic RAM organized as 1,048,576 words by 4 bits and designed to operate from a single +5-volt power supply. Advanced polycide technology using trench capacitors minimizes silicon area and provides high storage cell capacity, high performance, and high reliability. A single-transistor dynamic storage cell and CMOS circuitry throughout ensure minimum power dissipation, while an on-chip circuit internally generates the negative-voltage substrate bias—automatically and transparently.

The three-state I/O pins are controlled by  $\overline{\text{CAS}}$  independent of  $\overline{\text{RAS}}$ . After a valid read or read-modify-write cycle, data is held on the outputs by maintaining  $\overline{\text{CAS}}$  low. Data outputs return to high impedance when  $\overline{\text{CAS}}$  goes high. Fast-page read and write cycles can be executed by cycling  $\overline{\text{CAS}}$ .

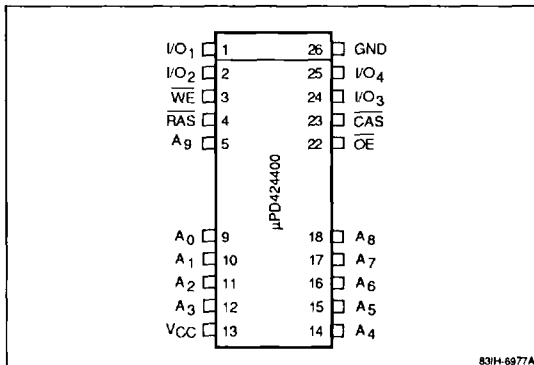
Refreshing may be accomplished by means of a  $\overline{\text{CAS}}$  before  $\overline{\text{RAS}}$  cycle that internally generates the refresh address. Refreshing may also be accomplished by means of  $\overline{\text{RAS}}$ -only refresh cycles or by normal read or write cycles on the 1,024 address combinations of  $A_0$  through  $A_9$  during a 16-ms refresh period.

## Features

- 1,048,576 by 4-bit organization
- Single +5-volt ±10% power supply
- Fast-page option
- Low power dissipation
- $\overline{\text{CAS}}$  before  $\overline{\text{RAS}}$  refreshing
- Multiplexed address inputs
- On-chip substrate bias generator
- TTL-compatible inputs and outputs
- Nonlatched, three-state outputs
- Low input capacitance
- 1024 refresh cycles every 16 ms
- 26/20-pin plastic SOJ or 20-pin plastic ZIP packaging

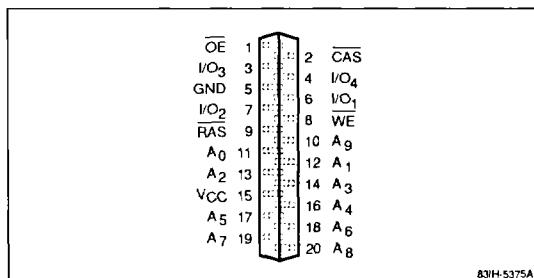
## Pin Configurations

### 26/20-Pin Plastic SOJ



831H-6977A

### 20-Pin Plastic ZIP



831H-5375A

**Pin Identification**

Name	Function
A <sub>0</sub> - A <sub>9</sub>	Address inputs
I/O <sub>1</sub> - I/O <sub>4</sub>	Data inputs and outputs
CAS	Column address strobe
OE	Output enable
RAS	Row address strobe
WE	Write enable
GND	Ground
V <sub>CC</sub>	+5-volt power supply

**Absolute Maximum Ratings**

Voltage on any pin relative to GND	-1.0 to +7.0 V
Operating temperature, T <sub>OPR</sub>	0 to +70 °C
Storage temperature, T <sub>STG</sub>	-55 to +125 °C
Short-circuit output current, I <sub>OS</sub>	50 mA
Power dissipation, P <sub>D</sub>	1.0 W

Exposure to Absolute Maximum Ratings for extended periods may affect device reliability; exceeding the ratings could cause permanent damage. The device should be operated within the limits specified under DC and AC Characteristics.

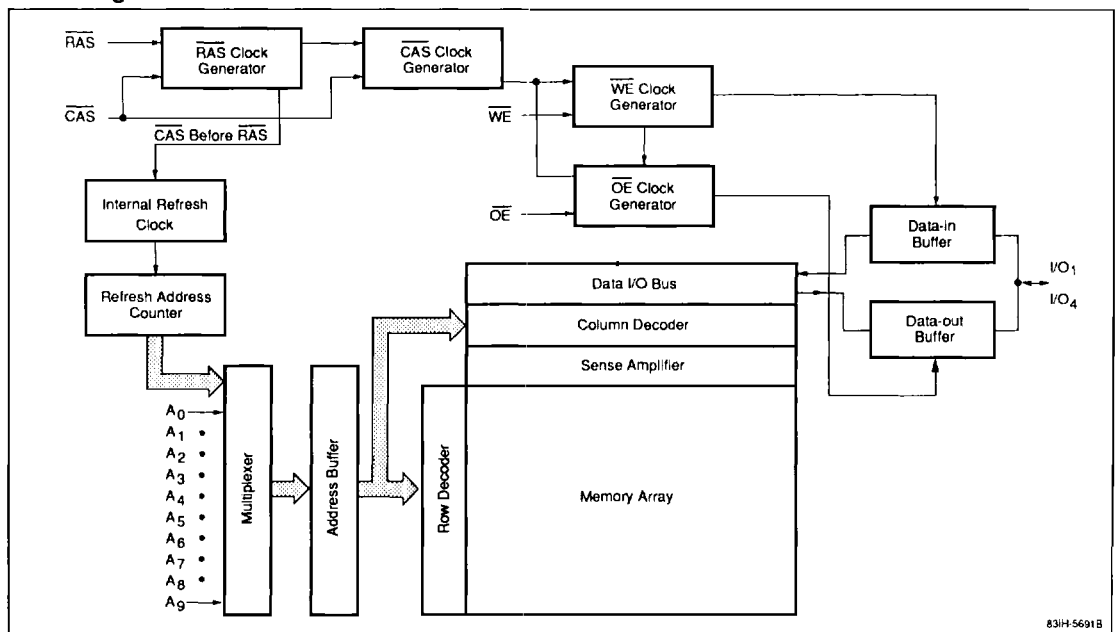
**Ordering Information**

Part Number	Row Access Time (max)	R/W Cycle Time (min)	Fast-Page Cycle (min)	Package
μPD424400LB-70	70 ns	140 ns	45 ns	26/20-pin plastic SOJ
LB-80	80 ns	160 ns	50 ns	
LB-10	100 ns	190 ns	60 ns	
μPD424400V-70	70 ns	140 ns	45 ns	20-pin plastic ZIP
V-80	80 ns	160 ns	50 ns	
V-10	100 ns	190 ns	60 ns	

**Notes:**

- (1) Contact your NEC sales representative for data sheet and product availability of the μPD424400-70.

**Block Diagram**



### Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit
Input voltage, high	$V_{IH}$	2.4		$V_{CC} + 1.0$	V
Input voltage, low	$V_{IL}$	-1.0		0.8	V
Supply voltage	$V_{CC}$	4.5	5.0	5.5	V
Ambient temperature	$T_A$	0		70	°C

### Capacitance

$T_A = 25\text{ }^\circ\text{C}; f = 1\text{ MHz}$

Parameter	Symbol	Max	Unit	Pins Under Test
Input capacitance	$C_{I1}$	5	pF	Addresses
	$C_{I2}$	7	pF	$\overline{RAS}$ , $\overline{CAS}$ , $\overline{WE}$ , $\overline{OE}$
Input/output capacitance	$C_O$	7	pF	I/O <sub>1</sub> - I/O <sub>4</sub>

### DC Characteristics

$T_A = 0\text{ to }+70\text{ }^\circ\text{C}; V_{CC} = +5.0 \pm 10\%$

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
Standby current	$I_{CC2}$			2.0	mA	$\overline{RAS} = \overline{CAS} \geq V_{IH}(\text{min}); I_O = 0\text{ mA}$
				1.0	mA	$\overline{RAS} = \overline{CAS} \geq V_{CC} - 0.2\text{ V}; I_O = 0\text{ mA}$
Input leakage current	$I_{I(L)}$	-10		10	μA	$V_{IN} = 0\text{ V to }V_{CC}$ ; all other pins not under test = 0V
Output leakage current	$I_{O(L)}$	-10		10	μA	$D_{OUT}$ disabled; $V_{OUT} = 0\text{ V to }V_{CC}$
Output voltage, low	$V_{OL}$			0.4	V	$I_{OL} = 4.2\text{ mA}$
Output voltage, high	$V_{OH}$	2.4			V	$I_{OH} = -5\text{ mA}$

### AC Characteristics

$T_A = 0\text{ to }+70\text{ }^\circ\text{C}; V_{CC} = +5.0\text{ V} \pm 10\%$

Parameter	Symbol	μPD424400-80		μPD424400-10		Unit	Test Conditions
		Min	Max	Min	Max		
Operating current, average	$I_{CC1}$		90		80	mA	$\overline{RAS}$ , $\overline{CAS}$ cycling; $t_{RC} = t_{RC}(\text{min})$ (Note 5)
Operating current, $\overline{RAS}$ -only refresh cycle, average	$I_{CC3}$		90		80	mA	$\overline{RAS}$ cycling; $\overline{CAS} \geq V_{IH}(\text{min})$ ; $t_{RC} = t_{RC}(\text{min})$ (Note 5)
Operating current, fast-page cycle, average	$I_{CC4}$		70		60	mA	$\overline{RAS} \leq V_{IL}$ ; $\overline{CAS}$ cycling; $t_{PC} = t_{PC}(\text{min})$ (Note 5)
Operating current, $\overline{CAS}$ before $\overline{RAS}$ refresh cycle, average	$I_{CC5}$		90		80	mA	$\overline{RAS}$ cycling; $\overline{CAS} \leq V_{IL}(\text{max})$ ; $t_{RC} = t_{RC}(\text{min})$ (Note 5)
Access time from column address	$t_{AA}$		40		50	ns	(Notes 3, 4, 7, 8)
Access time from $\overline{CAS}$ precharge (rising edge)	$t_{ACP}$		45		55	ns	(Notes 3, 4, 7, 8)
Column address setup time	$t_{ASC}$	0		0		ns	
Row address setup time	$t_{ASR}$	0		0		ns	
Column address to $\overline{WE}$ delay time	$t_{AWD}$	65		80		ns	(Note 14)
Access time from $\overline{CAS}$ (falling edge)	$t_{CAC}$		20		25	ns	(Notes 3, 4, 7, 8)
Column address hold time	$t_{CAH}$	15		20		ns	
$\overline{CAS}$ pulse width	$t_{CAS}$	20	10,000	25	10,000	ns	
$\overline{CAS}$ hold time for $\overline{CAS}$ before $\overline{RAS}$ refreshing	$t_{CHR}$	15		20		ns	
$\overline{CAS}$ to output in low-Z	$t_{CLZ}$	0		0		ns	(Note 4, 7)
$\overline{CAS}$ precharge time, fast-page cycle	$t_{CP}$	10		10		ns	
$\overline{CAS}$ precharge time	$t_{CPN}$	10		10		ns	
$\overline{CAS}$ to $\overline{RAS}$ precharge time	$t_{CRP}$	10		10		ns	(Note 10)
$\overline{CAS}$ hold time	$t_{CSH}$	80		100		ns	
$\overline{CAS}$ setup time for $\overline{CAS}$ before $\overline{RAS}$ refresh cycle	$t_{CSR}$	10		10		ns	

AC Characteristics (cont)

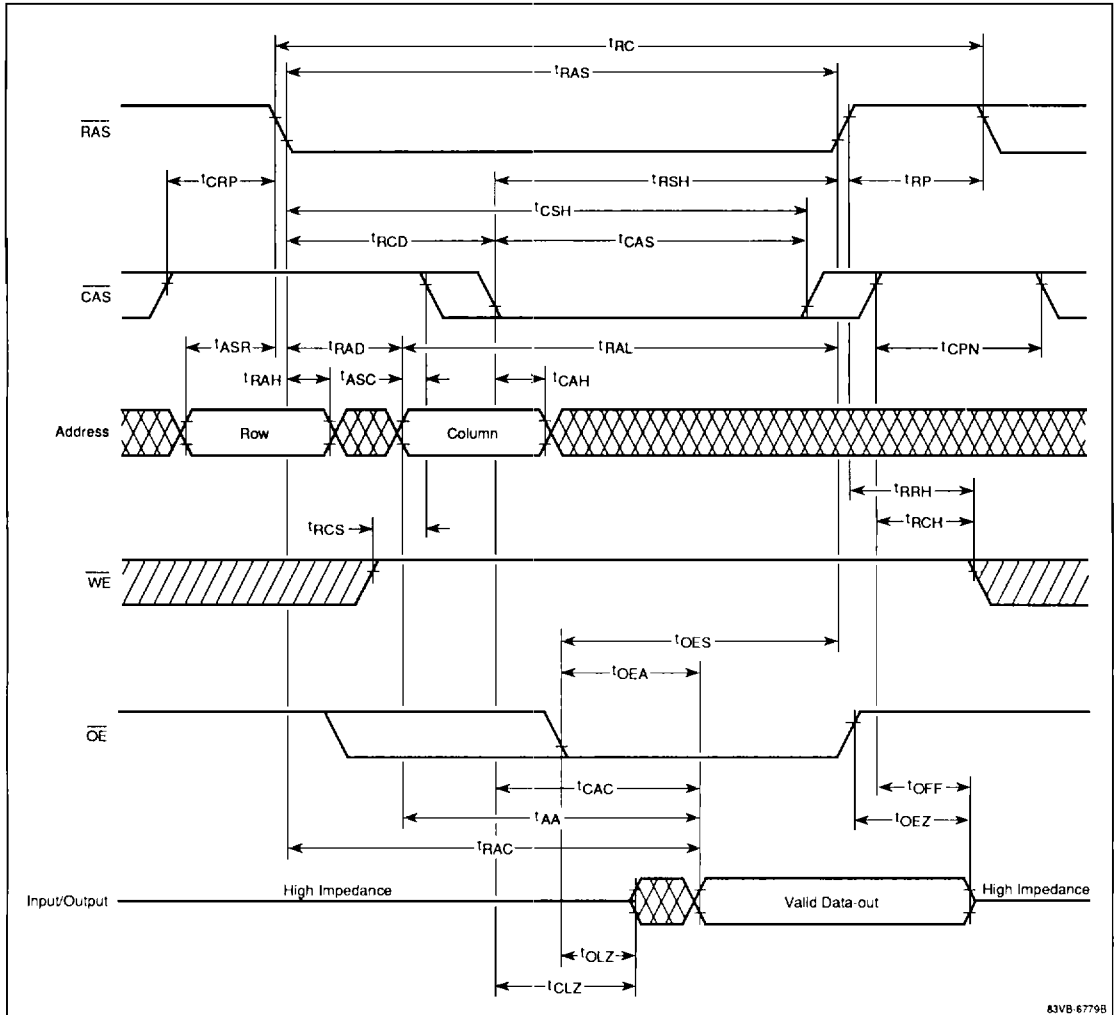
Parameter	Symbol	μPD424400-80		μPD424400-10		Unit	Test Conditions
		Min	Max	Min	Max		
CAS to WE delay	t <sub>CWD</sub>	45		55		ns	(Note 14)
Write command referenced to CAS lead time	t <sub>CWL</sub>	15		20		ns	
Data-in hold time	t <sub>DH</sub>	15		20		ns	(Note 13)
Data-in setup time	t <sub>DS</sub>	0		0		ns	(Note 13)
Access time from OE	t <sub>OEA</sub>		20		25	ns	(Notes 3, 4, 7, 8)
OE data delay time	t <sub>OED</sub>	20		25		ns	
OE command hold time	t <sub>OEH</sub>	0		0		ns	
OE to RAS inactive setup time	t <sub>OES</sub>	0		0		ns	
Output turnoff delay from OE	t <sub>OEZ</sub>	0	20	0	25	ns	(Note 9)
Output buffer turnoff delay	t <sub>OFF</sub>	0	20	0	25	ns	(Note 9)
OE to output in low-Z	t <sub>OLZ</sub>	0		0		ns	(Note 5, 7)
Fast-page read or write cycle time	t <sub>PC</sub>	50		60		ns	(Note 6)
Fast-page read-modify-write cycle time	t <sub>PRWC</sub>	100		120		ns	(Note 6)
Access time from RAS	t <sub>RAC</sub>		80		100	ns	(Notes 3, 4, 7, 8)
RAS to column address delay time	t <sub>RAD</sub>	17	40	17	50	ns	(Note 8)
Row address hold time	t <sub>RAH</sub>	12		12		ns	
Column address lead time referenced to RAS (rising edge)	t <sub>RAL</sub>	40		50		ns	
RAS pulse width	t <sub>RAS</sub>	80	10,000	100	10,000	ns	
RAS pulse width, fast-page cycle	t <sub>RASP</sub>	80	125,000	100	125,000	ns	
Random read or write cycle time	t <sub>RC</sub>	160		190		ns	(Note 6)
RAS to CAS delay time	t <sub>RCD</sub>	25	60	25	75	ns	(Note 8)
Read command hold time referenced to CAS	t <sub>RCH</sub>	0		0		ns	(Note 11)
Read command setup time	t <sub>RCS</sub>	0		0		ns	
Refresh period	t <sub>REF</sub>		16		16	ms	Address A <sub>0</sub> through A <sub>9</sub>
RAS precharge time	t <sub>RP</sub>	70		80		ns	
RAS precharge CAS hold time	t <sub>RPC</sub>	10		10		ns	
Read command hold time referenced to RAS	t <sub>RRH</sub>	10		10		ns	(Note 11)
RAS hold time	t <sub>RSH</sub>	20		25		ns	
Read-modify-write cycle time	t <sub>RWC</sub>	210		250		ns	(Note 6)
RAS to WE delay	t <sub>RWD</sub>	105		130		ns	(Note 14)
Write command referenced to RAS lead time	t <sub>RWL</sub>	20		25		ns	
Rise and fall transition time	t <sub>T</sub>	3	50	3	50	ns	(Note 4)
Write command hold time	t <sub>WCH</sub>	15		20		ns	(Note 12)
Write command setup time	t <sub>WCS</sub>	0		0		ns	(Note 14)
WE command hold time for CAS before RAS refreshing	t <sub>WHR</sub>	15		20		ns	
Write command pulse width	t <sub>WP</sub>	15		20		ns	(Note 12)
WE command setup time for CAS before RAS refreshing	t <sub>WSR</sub>	10		10		ns	

## Notes:

- (1) All voltages are referenced to GND.
- (2) An initial pause of 100 μs is required after power-up, followed by any eight  $\overline{\text{RAS}}$  cycles, before proper device operation is achieved. At the end of the initial power-up sequence, it is recommended that either a  $\overline{\text{RAS}}$ -only refresh or a  $\overline{\text{CAS}}$  before  $\overline{\text{RAS}}$  refresh cycle be executed while  $\overline{\text{WE}} \geq V_{\text{IH}}$  to ensure normal operation.
- (3) Ac measurements assume  $t_{\text{T}} = 5 \text{ ns}$ .
- (4)  $V_{\text{IH}}$  (min) and  $V_{\text{IL}}$  (max) are reference levels for measuring the timing of input signals. Transition times are measured between  $V_{\text{IH}}$  and  $V_{\text{IL}}$ .
- (5)  $I_{\text{CC1}}$ ,  $I_{\text{CC3}}$ ,  $I_{\text{CC4}}$ , and  $I_{\text{CC5}}$  depend on output loading and cycle rates. Specified values are obtained with the output open.  $I_{\text{CC3}}$  is measured assuming that all column address inputs are held at either a high level or a low level during  $\overline{\text{RAS}}$ -only refresh cycles.  $I_{\text{CC4}}$  is measured assuming that all column address inputs are switched only once during each fast-page cycle.
- (6) The minimum specifications are used only to indicate the cycle time at which proper operation over the full temperature range ( $T_{\text{A}} = 0$  to  $+70$  °C) is assured.
- (7) Load = 2 TTL ( $-1 \text{ mA}$ ,  $+4 \text{ mA}$ ) loads and 100 pF ( $V_{\text{OH}} = 2.0 \text{ V}$  and  $V_{\text{OL}} = 0.8 \text{ V}$ ).
- (8) If  $t_{\text{RCD}} \leq t_{\text{RCS}}$  (max) and  $t_{\text{RAD}} \leq t_{\text{RAD}}$  (max) access time is defined by  $t_{\text{RAC}}$  (max). If  $t_{\text{RCD}} \geq t_{\text{RCD}}$  (max) access time is defined by  $t_{\text{CAC}}$  (max) and if  $t_{\text{RAD}} \geq t_{\text{RAD}}$  (max) access time is defined by  $t_{\text{AA}}$  (max).
- (9)  $t_{\text{OFF}}$  (max) and  $t_{\text{OEZ}}$  (max) define the time at which the outputs achieve the open-circuit condition and are not referenced to  $V_{\text{OH}}$  or  $V_{\text{OL}}$ .
- (10) The  $t_{\text{CRP}}$  requirement should be applicable for  $\overline{\text{RAS}}/\overline{\text{CAS}}$  cycles preceded by any cycle.
- (11) Either  $t_{\text{RRH}}$  or  $t_{\text{RCH}}$  must be satisfied for a read cycle.
- (12) Parameter  $t_{\text{WFP}}$  is applicable for a delayed write cycle such as a read-write/read-modify-write cycle. For early write cycles, both  $t_{\text{WCS}}$  and  $t_{\text{WCH}}$  must be met.
- (13) These parameters are referenced to the falling edge of  $\overline{\text{CAS}}$  for early write cycles and to the falling edge of  $\overline{\text{WE}}$  for delayed write or read-modify-write cycles.
- (14)  $t_{\text{WCS}}$ ,  $t_{\text{RWD}}$ ,  $t_{\text{CWD}}$ , and  $t_{\text{AWD}}$  are restrictive operating parameters in read-write/read-modify-write cycles only. If  $t_{\text{WCS}} \geq t_{\text{WCS}}$  (min), the cycle is an early write cycle and the data I/O pins will remain open-circuit throughout the entire cycle. If  $t_{\text{CWD}} \geq t_{\text{CWD}}$  (min),  $t_{\text{RWD}} \geq t_{\text{RWD}}$  (min), and  $t_{\text{AWD}} \geq t_{\text{AWD}}$  (min), then the cycle is a read-write cycle and the data I/O pins will contain data read from the selected cells. If neither of the above conditions is met, the condition of the data I/O pins (at access time and until  $\overline{\text{CAS}}$  returns to  $V_{\text{IH}}$ ) is indeterminate.
- (15) Assumes that the test mode has been set. Contact your NEC Electronics sales representative for more details. A test mode may be initiated by executing a  $\overline{\text{CAS}}$  before  $\overline{\text{RAS}}$  refresh cycle with  $\overline{\text{WE}}$  held at  $V_{\text{IL}}$ . This mode also may inadvertently be initiated during power-up because external control of the signal lines is very difficult during this period. It is therefore recommended that while  $\overline{\text{WE}}$  is held at  $V_{\text{IH}}$ , either a  $\overline{\text{RAS}}$ -only or  $\overline{\text{CAS}}$  before  $\overline{\text{RAS}}$  refresh cycle should be executed at any time after the end of the initial power-up sequence to ensure normal device operation.

Timing Waveforms

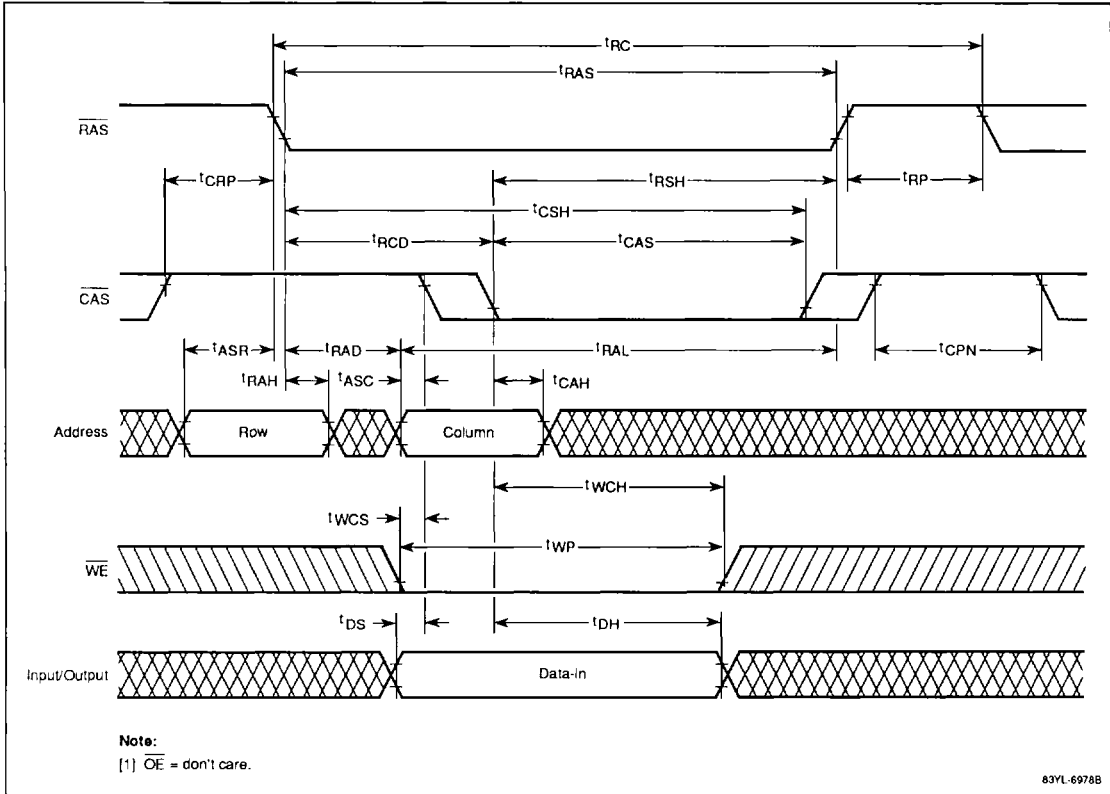
Read Cycle



83VB 67798

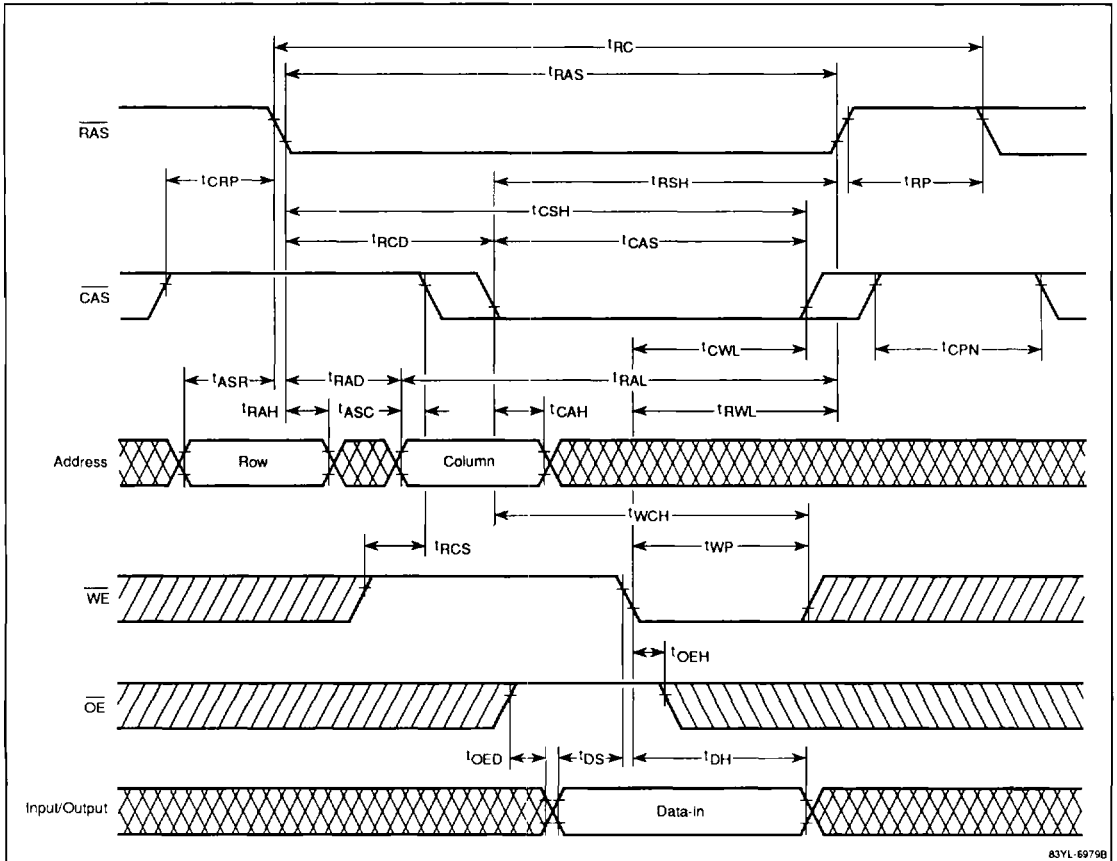
## Timing Waveforms (cont)

### Early Write Cycle



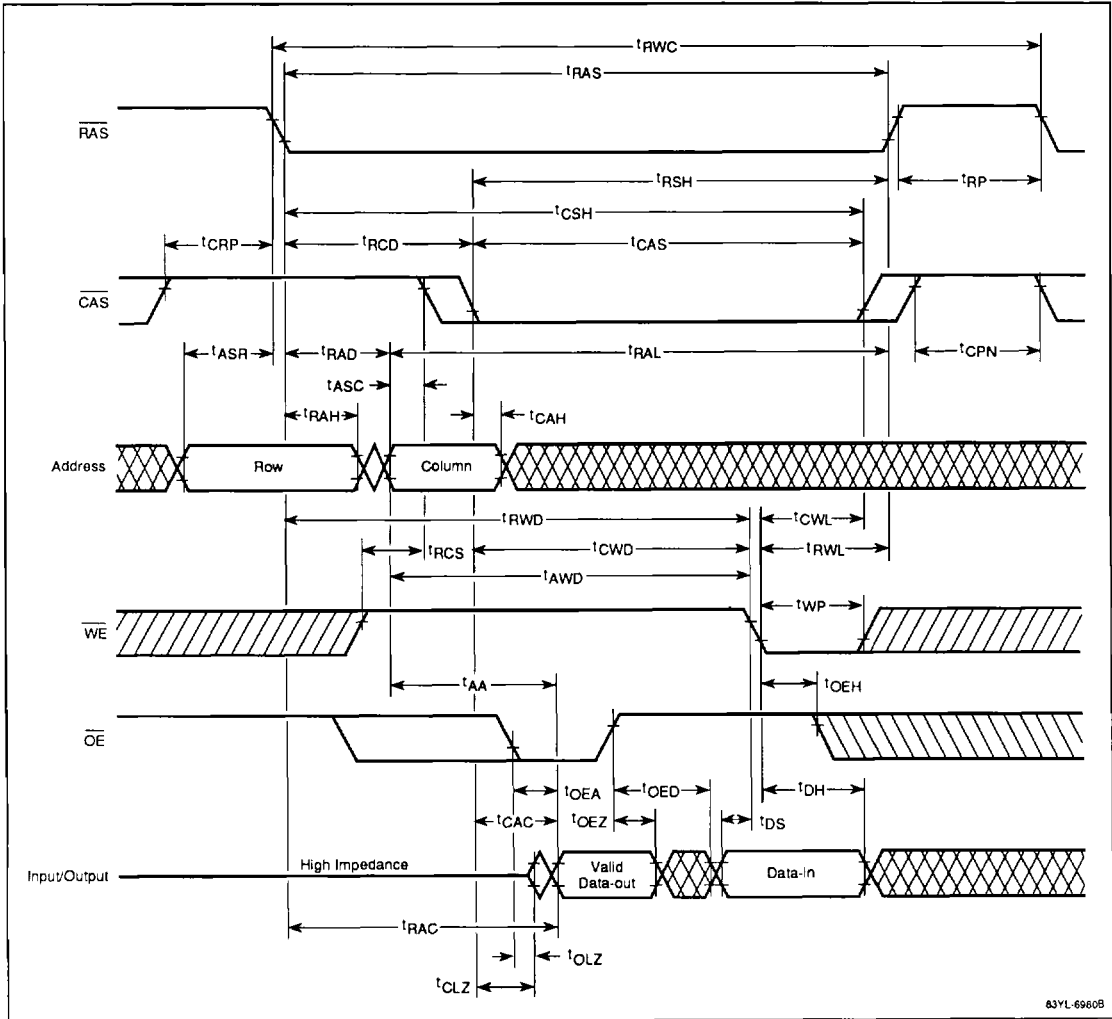
Timing Waveforms (cont)

Late Write Cycle



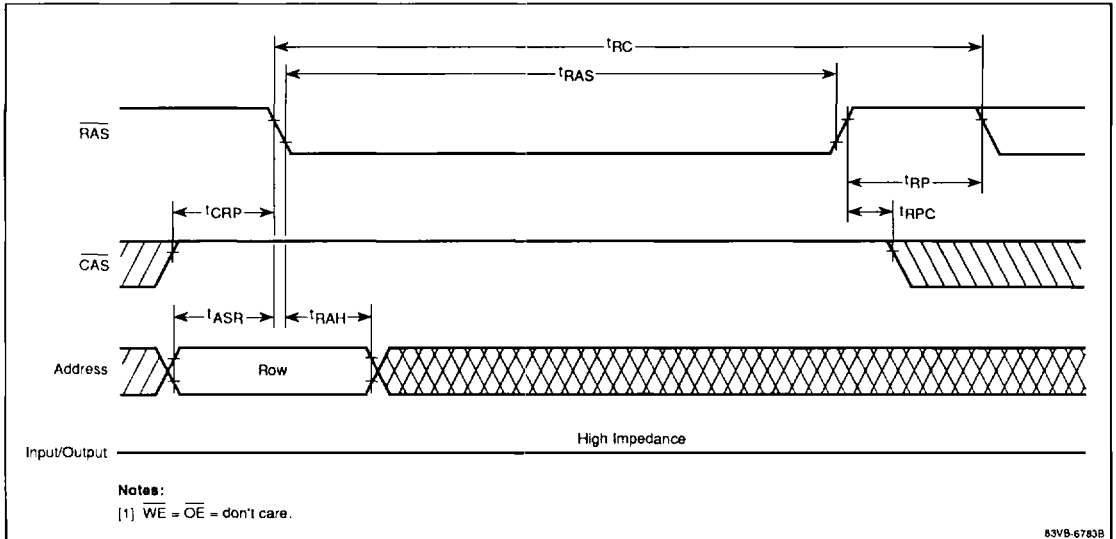
## Timing Waveforms (cont)

### Read-Write/Read-Modify-Write Cycle

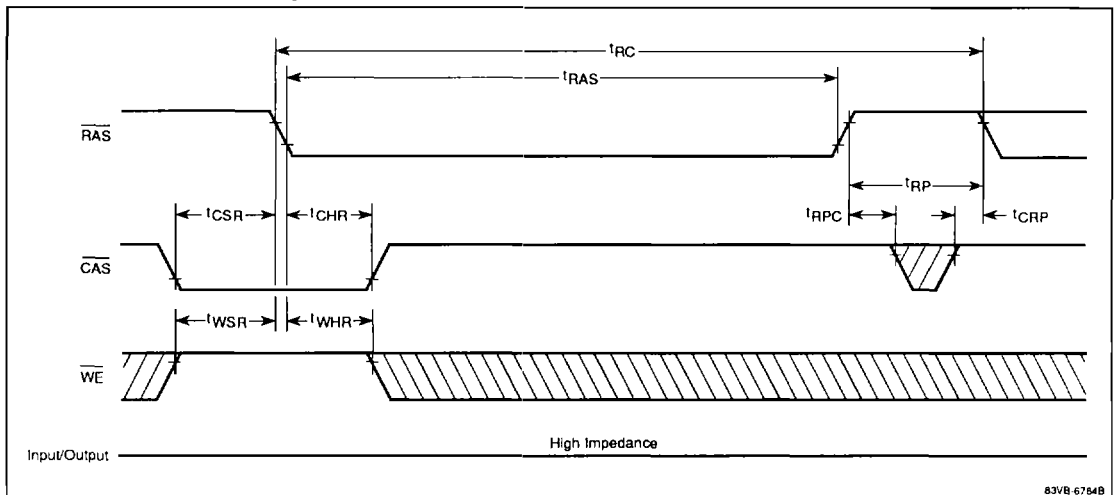


Timing Waveforms (cont)

**RAS-Only Refresh Cycle**

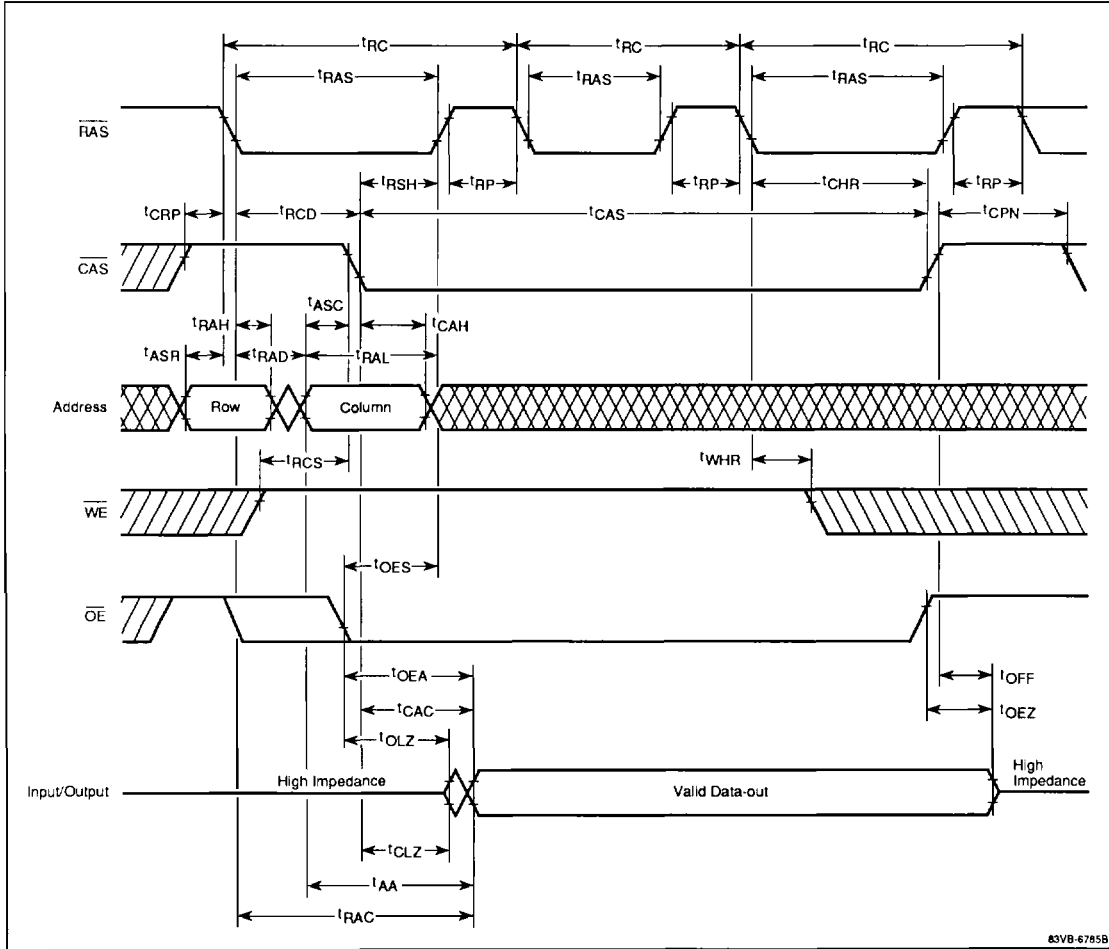


**CAS Before RAS Refresh Cycle**



## Timing Waveforms (cont)

### Hidden Refresh Cycle

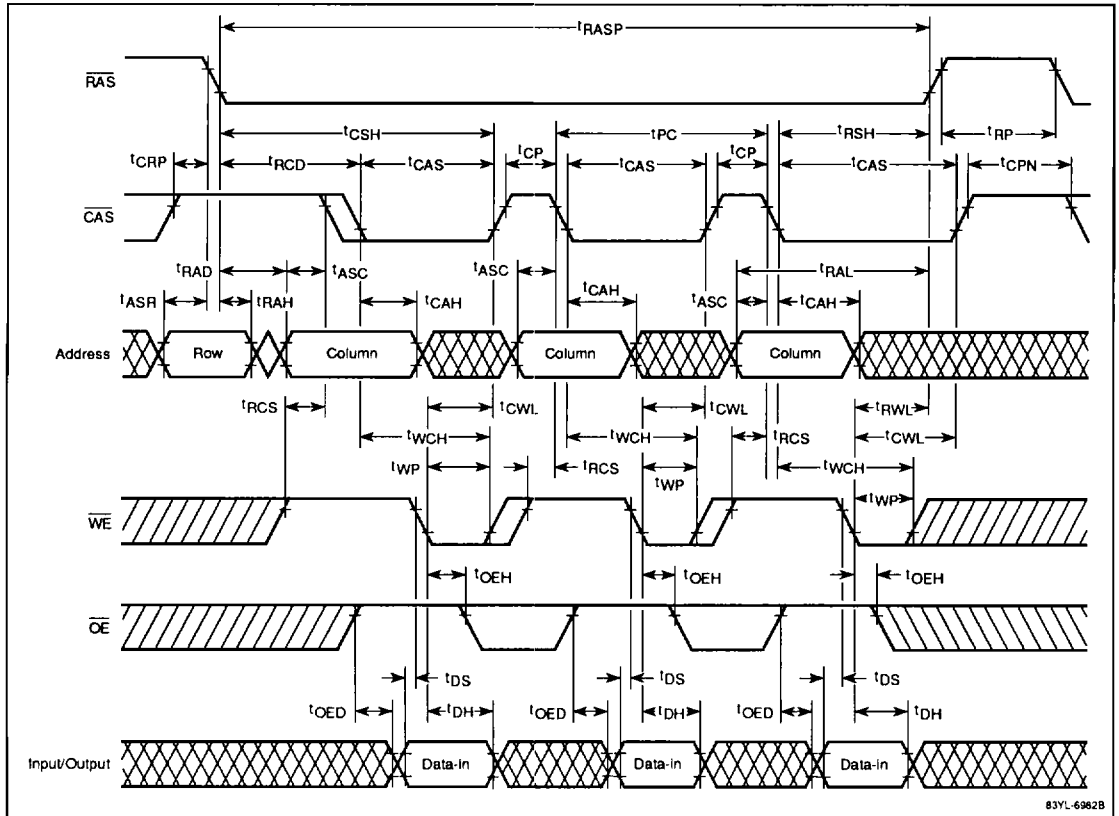






Timing Waveforms (cont)

Fast-Page Late Write Cycle



83YL-6982B

## Timing Waveforms (cont)

### Fast-Page Read-Write/Read-Modify-Write Cycle

